ABSOCIATION CONNECTING ALECTROMICS INDUSTRIES®	IPC, Bannock	burn, Illinois. A	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declar he declaratio	ration c n encor	of the substand mpasses all lo	ces with wer lev	in the manuface al materials for	cturer listed i r which the r	tem. N nanufao	ote: if the	e item is an as s engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					terials and M	ials and Mfg Information				
upplier Information																
Company name*	Company unique ID			Unique ID Authority					Respon	Response Date*						
onsemi									2024-04-26							
Contact Name	Title - Conta	Title - Contact			Phone - Contact*					Email -	Email - Contact*					
Product-Env-Stewards	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
uthorized Representative*	Title - Representative			Phone - Representative*				Email -	Email - Representative*							
Product-Env-Stewards	Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com						
Requester Item Number	Mfr Iter	n Number Mfr Item Name				Effective Date V		version	sion Manufacturing Site			Weight*		UOM	Unit Type	
	FDMA3	023PZ	Dual ST3 Pch 30V/8V Z MLP			2024-04-26			TH2			9.879		mg	Each	
Ianufacturing Proccess Inform	ation					1			- I					1		
Terminal Plating / Grid Array M	Iaterial '	Ferminal Base	Alloy	J-STD-020 MS	L Rating	Peak Process		s Body Temperature Max Time at Peal		eak Tempera	Temperature Numb		of Reflow Cyc	eles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		С		30		ids 3	3			
omments																
vel 1 - maximum time at peak tempera	ture during so	ldering is 10-3	0 seconds													
or more information regarding materia	l composition	please refer to	page 3													

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.569	mg	Supplier	Silicon (Si)	7440-21-3		0.569	mg
Die Attach	0.108	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.0065	mg
			Supplier	Silver (Ag)	7440-22-4		0.088	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.0065	mg
			Supplier	Misc.	Proprietary Data		0.0005	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.0065	mg
Lead Frame	4.24	mg	Supplier	Zinc (Zn)	7440-66-6		0.0051	mg
			Supplier	Iron (Fe)	7439-89-6		0.0996	mg
			Supplier	Copper (Cu)	7440-50-8		4.134	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0013	mg
Mold Compound-Black	4.878	mg	Supplier	Carbon Black (C)	1333-86-4		0.0244	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.2926	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.3171	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2439	mg
Plating NiPdAu	0.049	mg	Supplier	Palladium (Pd)	7440-05-3		0.0025	mg
			В	Nickel (Ni)	7440-02-0		0.0441	mg
			Supplier	Gold (Au)	7440-57-5		0.0025	mg
Wire Bond - Cu	0.035	mg	Supplier	Copper (Cu)	7440-50-8		0.035	mg